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L Number	Hits	Search Text	DB	Time stamp
2	2561	((elimina\$4 reduce\$ decreas\$4 lower\$4) and	USPAT;	2001/04/06 14:42
		stress).ti.	EPO; JPO;	
			Derwent;	
			IBM TDB	
3	2070	((elimina\$4 reduce\$ decreas\$4 lower\$4)	USPAT;	2001/04/06 14:43
		near4 stress).ti.	EPO; JPO;	
			Derwent; IBM TDB	
4	1415	((e1imina\$4 reduce\$ decreas\$4 lower\$4)	USPAT;	2001/04/06 15:10
4	1415	near4 stress).clm.	EPO; JPO;	2001/04/08 13.10
		near i belebby i exili	Derwent;	
			IBM TDB	
5	31	(((elimina\$4 reduce\$ decreas\$4 lower\$4)	USPAT;	2001/04/06 14:50
		near4 stress).clm.) and cold near4 work\$3	EPO; JPO;	
			Derwent;	
	_		IBM TDB	, ,
6	9	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	USPAT;	2001/04/06 14:51
		near4 stress).clm.) and cold near4 work\$3).clm.	EPO; JPO;	
		work\$3).cim.	Derwent; IBM TDB	
7	308	((elimina\$4 reduce\$ decreas\$4 lower\$4)	USPAT;	2001/04/06 15:17
′	300	near4 stress) and (burnish\$4	EPO; JPO;	2301,01,00 13.17
		polish\$4).clm.	Derwent;	
			IBM TDB	
8	1	((elimina\$4 reduce\$ decreas\$4 lower\$4)	USPAT;	2001/04/06 15:13
		near4 stress and (burnish\$4 polish\$4) and	EPO; JPO;	
		cold).clm.	Derwent;	
_			IBM TDB	
9	34	((elimina\$4 reduce\$ decreas\$4 lower\$4)	USPAT;	2001/04/06 15:21
		near4 stress) and (burnish\$4 polish\$ and	EPO; JPO;	
		compress\$4).clm.	Derwent; IBM TDB	
10	1	(cold and(elimina\$4 reduce\$ decreas\$4	USPAT;	2001/04/06 15:25
	_	lower\$4) near4 stress and (burnish\$4	EPO; JPO;	2002,01,00
		polish\$) and compress\$4).clm.	Derwent;	
			IBM TDB	
-	81	73/862.043.ccls.	USPAT	2001/03/30 12:30
_	235		USPAT	2001/03/30 12:31
_	79		USPAT	2001/04/03 16:14 2001/03/30 13:06
<u>-</u>	235 599	73/826.ccls. 73/\$7.ccls. and method and tensile near3	USPAT;	2001/03/30 13:06
_	J 9 9	stress	EPO; JPO;	2001/04/03 10.10
			Derwent;	
			IBM TDB	
-	14		USPAT;	2001/04/03 16:29
		stress and pressure).clm.)	EPO; JPO;	
	!		Derwent;	
	,	73/\$7.ccls. and ((method and tensile near3	IBM TDB USPAT;	2001/04/03 16:19
_	1	stress and pressure).clm.) and cold near2	EPO; JPO;	2001/04/03 10:19
		work\$2	Derwent;	
			IBM TDB	
_	0	73/\$7.ccls. and method and measure and	USPAT;	2001/04/03 16:34
		pressure and (tensile near3 stress) and	EPO; JPO;	
		(cold near2 work\$2) and burnish\$3	Derwent;	
			IBM TDB	0001/04/00 15 55
-	14	1 - 1 1 - 1 - 1	USPAT;	2001/04/03 16:21
		pressure and (tensile near3 stress) and	EPO; JPO;	
		cold near2 work\$2	Derwent; IBM TDB	
_	9	73/\$7.ccls. and method and measure and	USPAT;	2001/04/03 16:27
		pressure and (tensile near3 (stress	EPO; JPO;	2001,01,00 10.27
	İ	tension)) and (cold near2 work\$3) and	Derwent;	
		(burnish\$3 rub\$3 polish\$3 smooth\$3)	IBM TDB	
_	47	73/\$7.ccls. and ((method and tensile near3	USPAT;	2001/04/03 16:39
	1	stress and pressure) and (reduce lower	EPO; JPO;	
		short).clm.)	Derwent;	
	L		IBM TDB	

_	0	(method and measure and pressure and	USPAT;	2001/04/03 16:37
		(tensile near3 stress) and (cold near2	EPO; JPO;	
		work\$2) and burnish\$3).clm.	Derwent;	ļ
			IBM TDB	
_	1	method and measure and pressure and	USPAT;	2001/04/03 16:34
		(tensile near3 stress) and (cold near2	EPO; JPO;	
		work\$2) and burnish\$3	Derwent;	
			IBM TDB	
_	15	(method and measure and pressure and	USPAT;	2001/04/03 16:43
		(tensile near3 stress) and (cold near2	EPO; JPO;	
		work\$2) and (burnish\$3 rubbing rub smooth	Derwent;	
	İ	smoothing polish polishing))	IBM TDB	
_	1	(method and measure and (reduce lower	USPAT;	2001/04/03 16:45
		decrease) and (tensile near3 stress) and	EPO; JPO;	
		(cold near2 work\$2) and ((burnish\$3	Derwent;	
		rubbing rub smooth smoothing polish	IBM TDB	
		polishing) near3 (device apparatus		
		machine)))		